

LOW PROFILE RESIN SEALED SURFACE MOUNT PACKAGE - XCR1 Series

FEATURES

- 1.55 mm Maximum Height, Ceramic Base and Cover SMT Package
- Microprocessor Crystal Specifications, AT-cut, Important Low Frequency Range
- Industry de factor Standard Footprint
- Excellent for High Density Surface Mounting

SPECIFICATIONS

Frequency Range 3.500 MHz to 30.000 MHz Standard Frequencies Standard Frequency Table

Resonance Mode 1 = Fundamental

Calibration Tolerance @25°C $A = \pm 50 \text{ ppm}$; $B = \pm 30 \text{ ppm}$ Frequency Stability Ref @25°C $50 = \pm 50 \text{ ppm}$; $30 = \pm 30 \text{ ppm}$

Temperature Range $A = 0^{\circ}\text{C to } 70^{\circ}\text{C}; B = -40^{\circ}\text{C to } 85^{\circ}\text{C}; C = -10^{\circ}\text{C to } 60^{\circ}\text{C}$

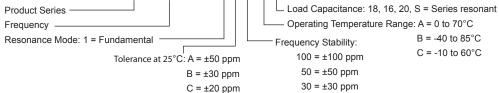
Standard Stability $30C = \pm 30 \text{ ppm } / -10^{\circ}\text{C} \text{ to } 60^{\circ}\text{C}$ Crystal Aging $\pm 5 \text{ ppm Maximum } / 1\text{st year}$

Operatable Temperature Range -40°C to 85°C Storage Temperature -55°C to 125°C

Load Capacitance (CL) CL = 18 pF (Standard), 16 pF, 20 pF, others, or S = Series resonant

Shunt Capacitance 7.0 pF Maximum **Drive Level** 0.1 mW Typical

Creating a Part Number XCR1- 3M579545 -1 B 30 C 18 -options



Equivalent Series Resistance

Frequency (MHz)	Mode	Max ESR (Ohms)
3.500 - 3.999	Fund	200
4.000 - 5.999	Fund	150
6.000 - 9.999	Fund	100
10.000 - 13.999	Fund	80
14.000 - 30.000	Fund	50

OUTLINE DRAWING

